

2SK1637

Silicon N Channel MOS FET

REJ03G0962-0200

(Previous: ADE-208-1305)

Rev.2.00 Sep 07, 2005

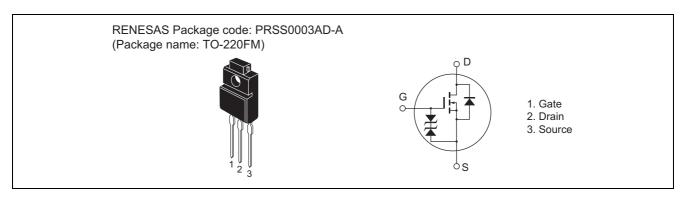
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	600	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	I _D	4	А
Drain peak current	I _{D(pulse)} *1	16	А
Body to drain diode reverse drain current	I _{DR}	4	А
Channel dissipation	Pch ^{*2}	35	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at $T_C = 25^{\circ}C$

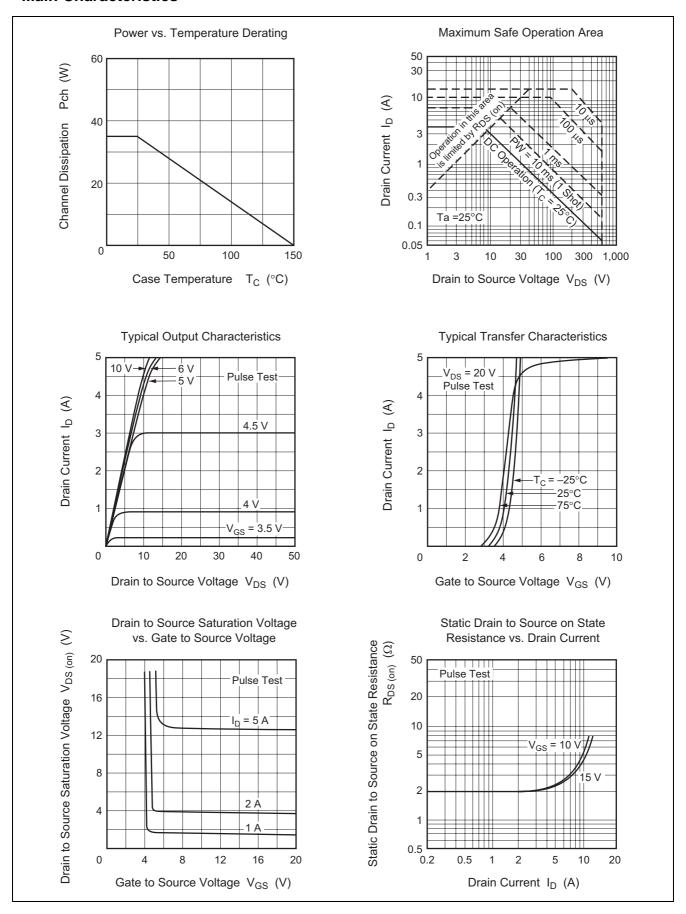
Electrical Characteristics

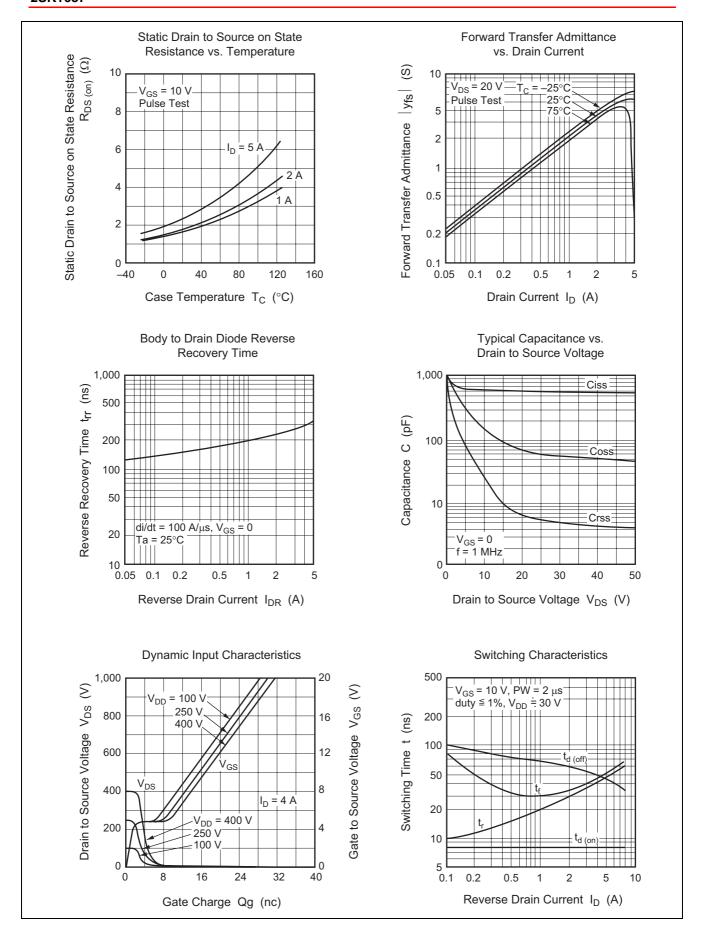
 $(Ta = 25^{\circ}C)$

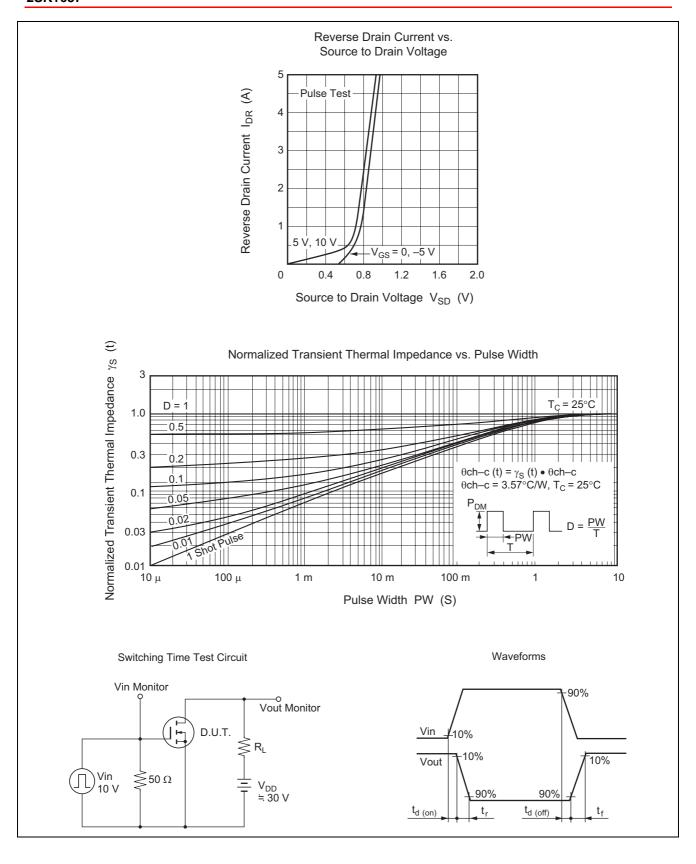
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	600	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±30	_	_	V	$I_G = \pm 100 \mu\text{A}, V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	250	μA	V _{DS} = 500 V, V _{GS} = 0
Gate to source cutoff voltage	V _{GS(off)}	2.0	_	3.0	V	I _D = 1 mA, V _{DS} = 10 V
Static drain to source on state resistance	R _{DS(on)}	_	1.8	2.4	Ω	$I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}^{*3}$
Forward transfer admittance	y _{fs}	2.2	3.5	_	S	$I_D = 2 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$
Input capacitance	Ciss	_	600	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	140	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	25	_	pF	
Turn-on delay time	t _{d(on)}	_	8	_	ns	$I_D = 2 A, V_{GS} = 10 V,$
Rise time	t _r	_	30	_	ns	$R_L = 15 \Omega$
Turn-off delay time	t _{d(off)}	_	60	_	ns	
Fall time	t _f	_	35	_	ns	
Body to drain diode forward voltage	V_{DF}	_	0.9	_	V	$I_F = 4 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}		300	_	ns	$I_F = 4 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A/}\mu\text{s}$

Note: 3. Pulse test

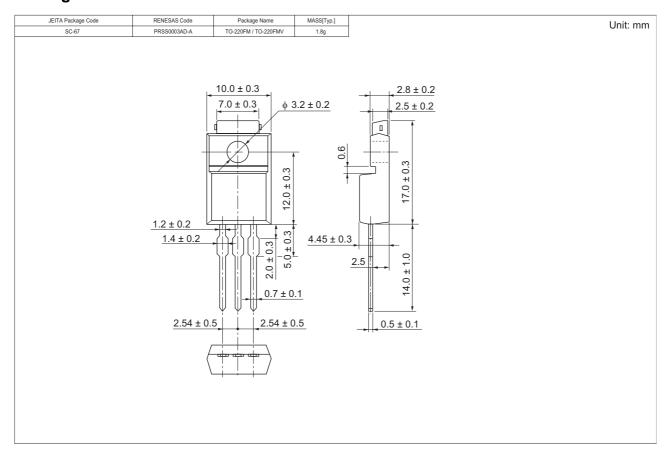
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK1637-E	500 pcs	Box (Sack)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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